

Title (en)

METHOD AND DEVICE FOR EMBEDDING AT LEAST ONE ELECTRONIC COMPONENT IN A SUBSTRATE

Title (de)

VERFAHREN UND VORRICHTUNG ZUM EINBETTEN MINDESTENS EINES ELEKTRONISCHEN BAUELEMENTS IN EINEM TRÄGER

Title (fr)

PROCÉDÉ ET DISPOSITIF PERMETTANT D'INCORPORER AU MOINS UN COMPOSANT ÉLECTRONIQUE DANS UN SUPPORT

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Application

EP 18703987 A 20180207

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Abstract (en)

[origin: WO2018146130A1] The present invention relates to a method and a device for embedding at least one electronic component (1) into a substrate (2). In this respect, the at least one component (1) is fixed in or on a receiving unit (3), and the substrate (2) is produced by applying a substrate material into or onto the receiving unit (3) in layers, the at least one component (1) being embedded into the substrate material as the result of said application in layers.

IPC 8 full level

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